REVISION HISTORY Notes - Unless otherwise noted DESCRIPTION DATE ENG REV 1. Resistances values in Ohms 2. Capacitance values in microfarads (uF) 04-08-2011 Α1 INITIAL SCHEMATIC AIY 3. All 0.1uF and 0.01uF capactors are decoupling and should be placed near the IC they are shown with. A2 REMOVED ANALOG SWITCHES 05-12-2011 AKS CHANGED FEEDBACK CHANGED THE SIZE OF THE SENSE RESITORS 05-25-2011 A3 AKS ADDED PULL-UP/PULL-DOWN ON SPI LINES REMOVED 0-OHM RESISTORS ON CURRENT SENSE В1 FIXED DRV8301 CURRENT SENSE POLARITY NO-POP ALL EXTERNAL CURRENT SENSE COMPONENTS 07-14-2011 JPW CHANGED C14 TO 25V 0805 PACKAGE FETS CHANGED TO VISHAY SUM110N06-3M9H CHANGED CURRENT SENSE RESISTORS TO 2mOHM RECONFIGURED DC BUS CAPS SPLIT POWER CONNECTOR INTO TWO CONNECTORS C1 LAYOUT CHANGES TO IMPROVE GROUND CONNECTIONS FOR 08-12-2011 AKS DE-COUPLING CAPACITORS C10, C14, C72 CREATED BOM VARIANT FOR DRV8302 CHANGED R12, R13, R21 TO 1K CHANGED R43, R47 TO 1K (DRV8302 ONLY) POPULATED EXTERNAL GAIN OP-AMPS AND CHANGED 01-18-2012 D1 CONNECTIONS FOR THESE TO DAUGHTER CARD

Page 1 - Title - Index - Revisions

Page 2 - Block Diagram

Page 3 - DRV8301/DRV8302

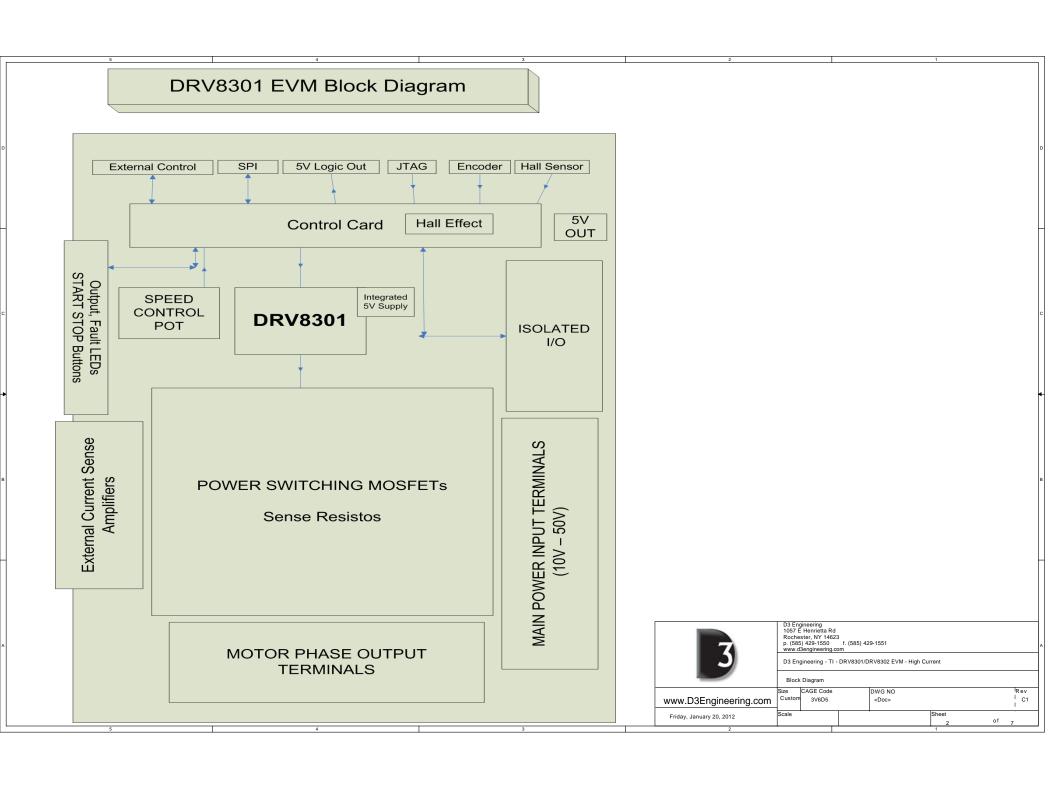
Page 4 - Isolation Circuitry

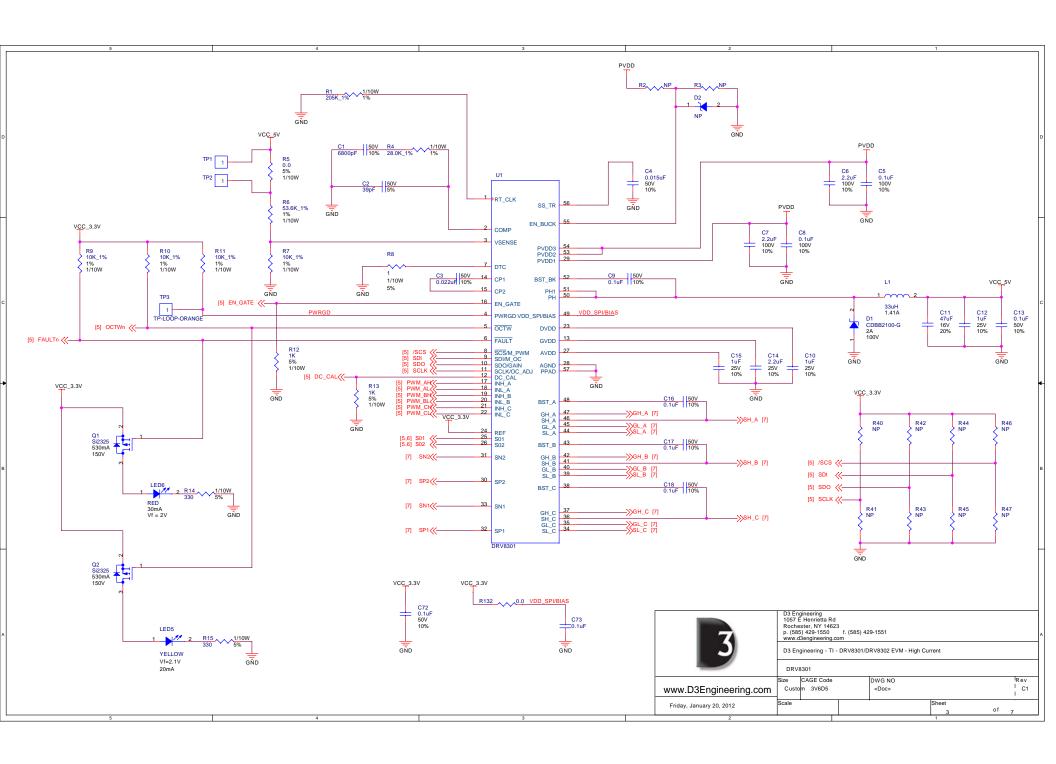
Page 5 - DIMM Socket - Connectors - Switches

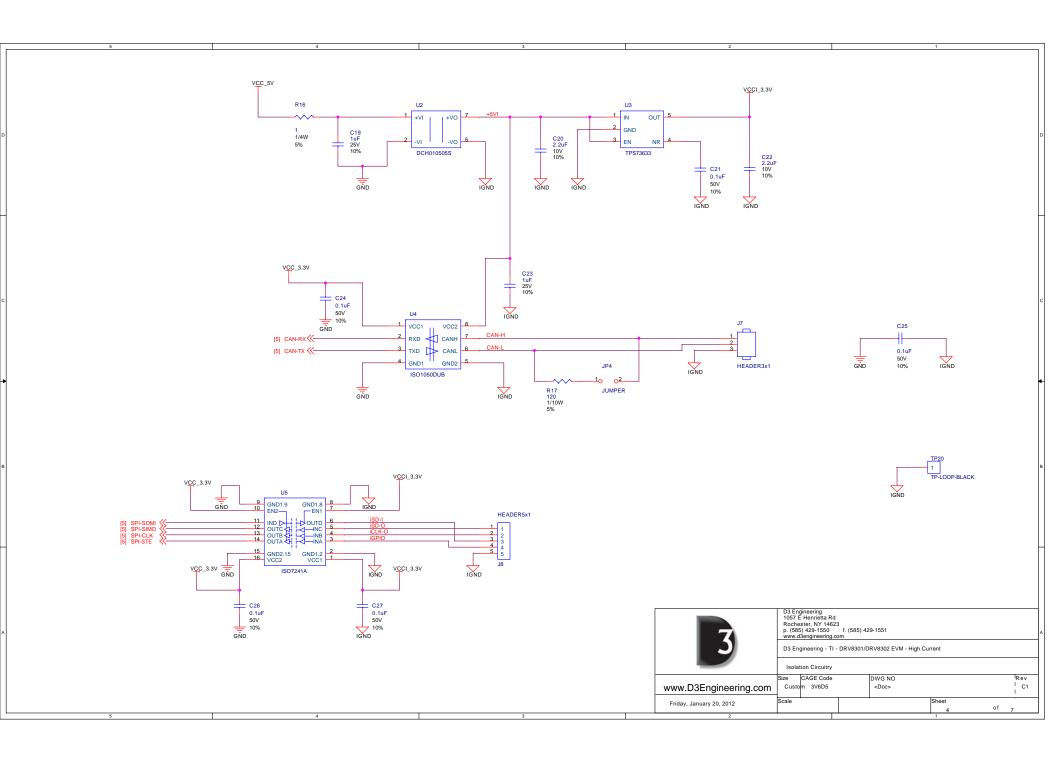
Page 6 - Power Input - Voltage Regulators - Current Sense Amplifiers

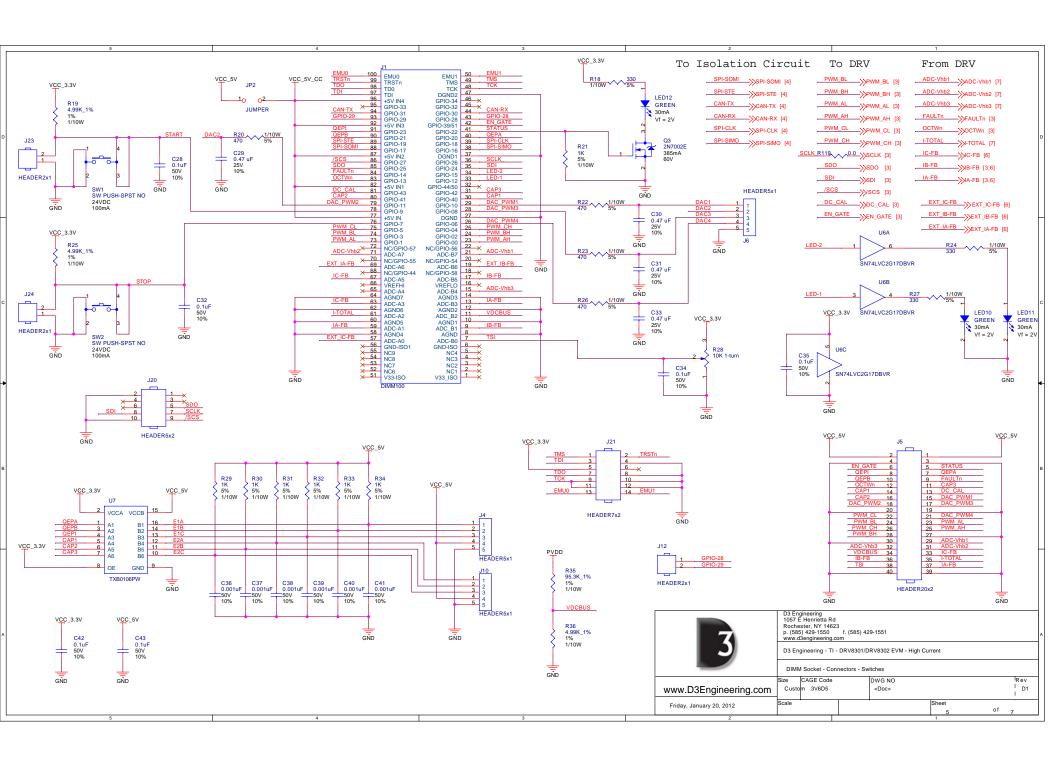
Page 7 - Half Bridges - Motor Output

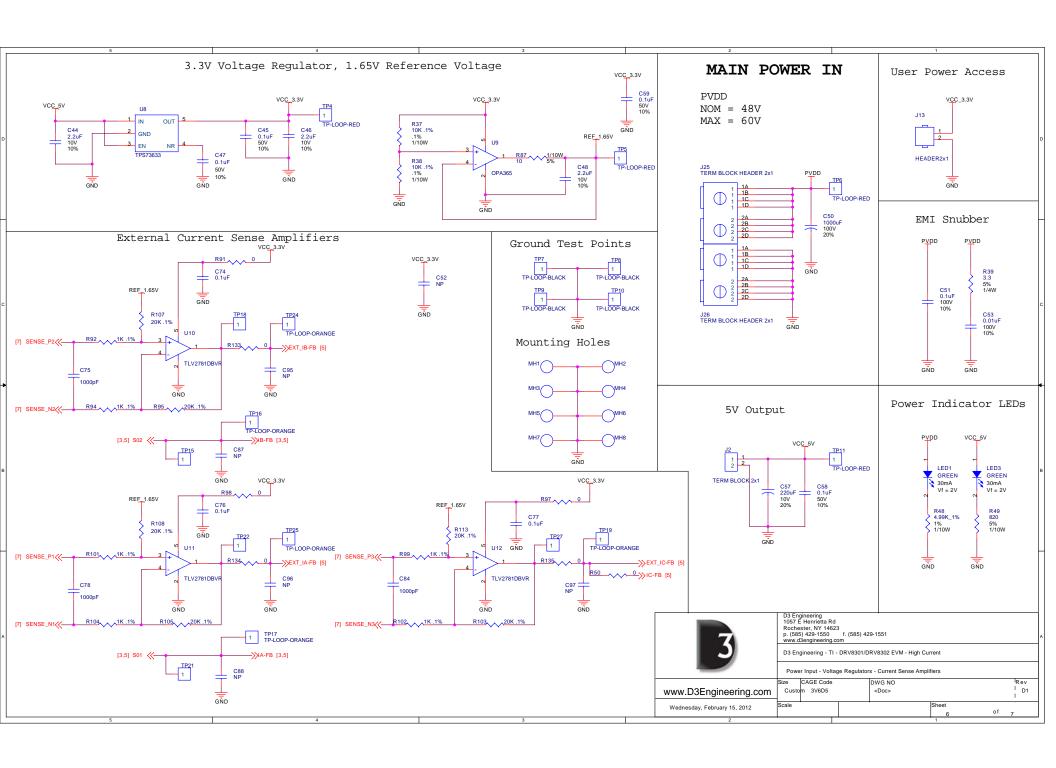
3	D3 Engineering 1057 E Henrietta Rd Rochester, NY 14623 p. (585) 429-1550 www.d3engineering.com D3 Engineering - TI - DRV8301/DRV8302 EVM - High Current							А
www.D3Engineering.com		- Index - Revis CAGE Code 3V6D5	ions	DWG NO <doc></doc>			Rev I D1	
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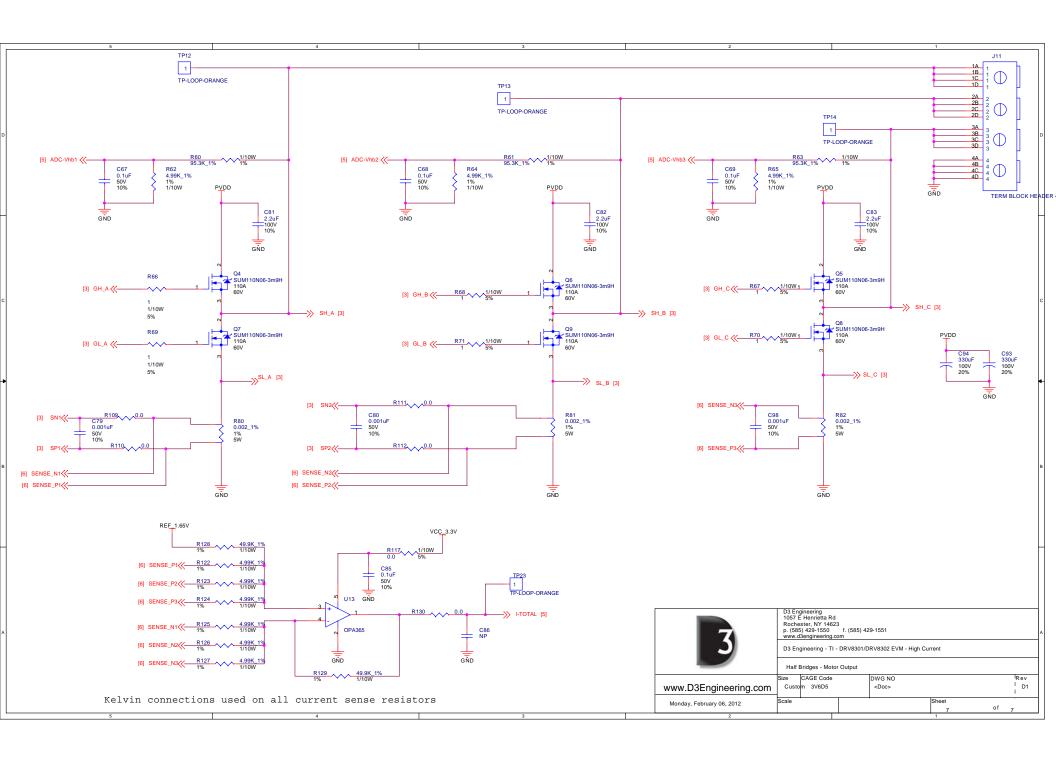












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